

# ***Safe Send Final Design Review***

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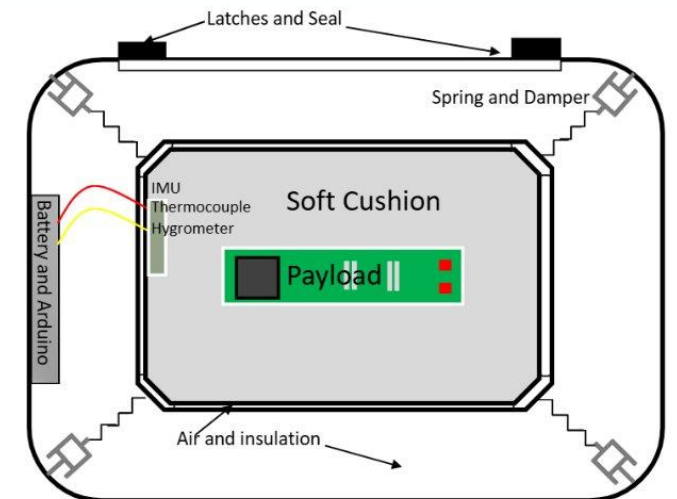
05/02/25



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# Problem Overview

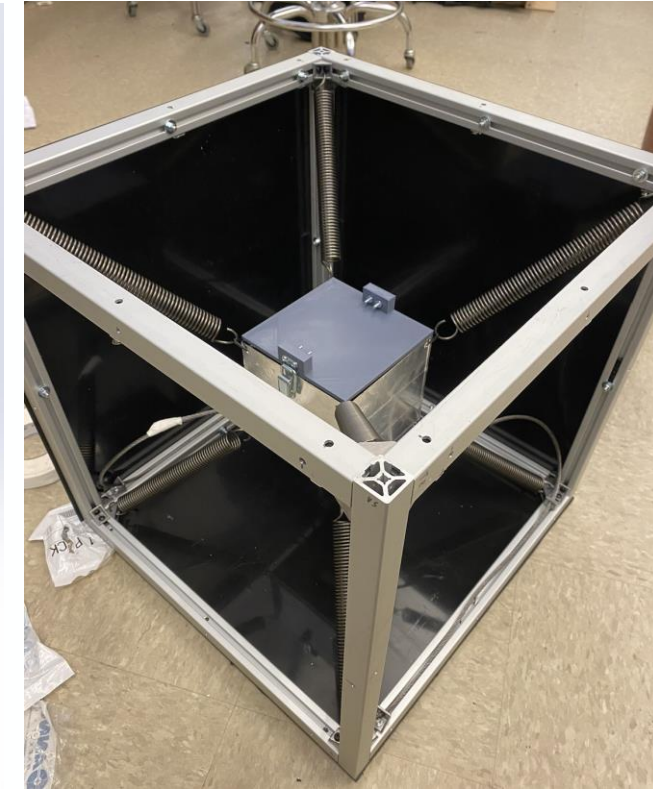
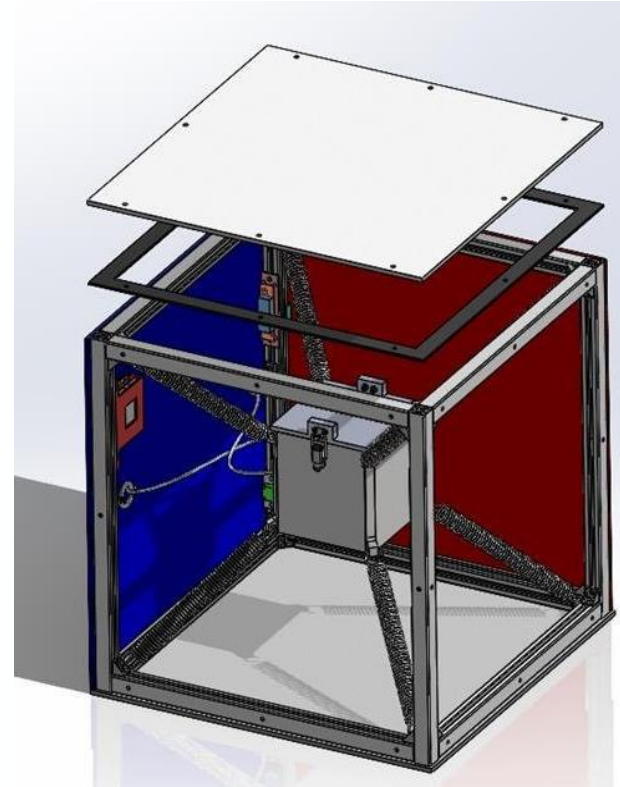
- Shipping solution for precision assemblies and components
- Key stakeholders include precision engineering and shipping companies
  - Optics Companies
  - Microelectronics
  - Biomedical
- Tracking provides engineering companies information about shipping status
- Key Requirements
  - Minimize acceleration on payload to below 15 g from a 1-meter drop
  - Protect payload from heat and moisture
  - Track acceleration, temp, humidity



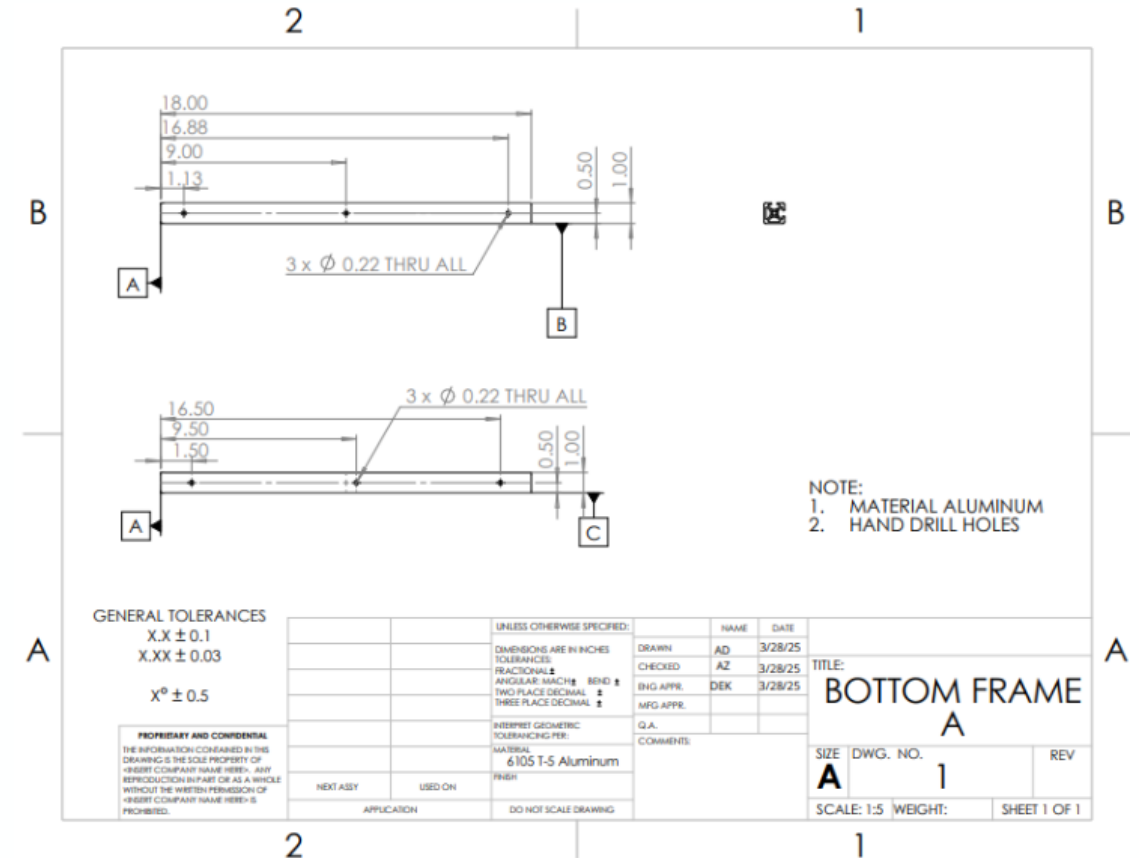
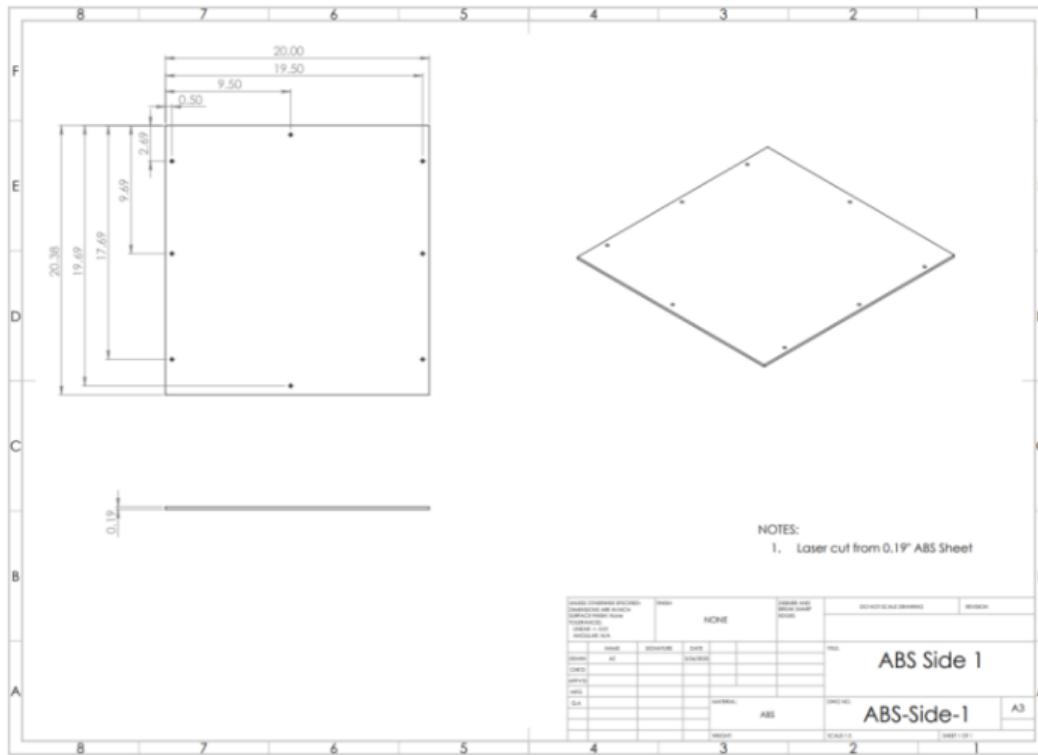
# Manufacturing

## Outer Shell and Frame

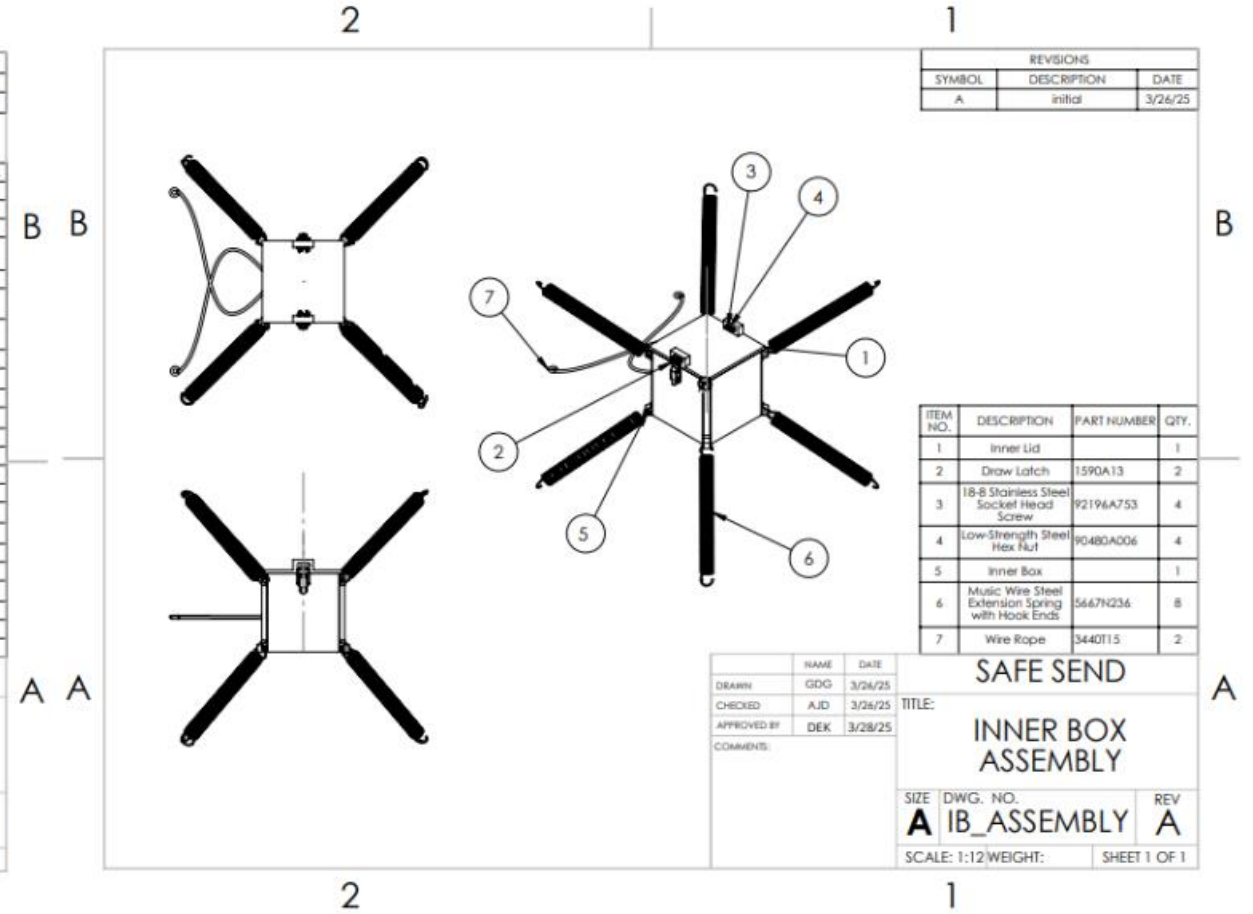
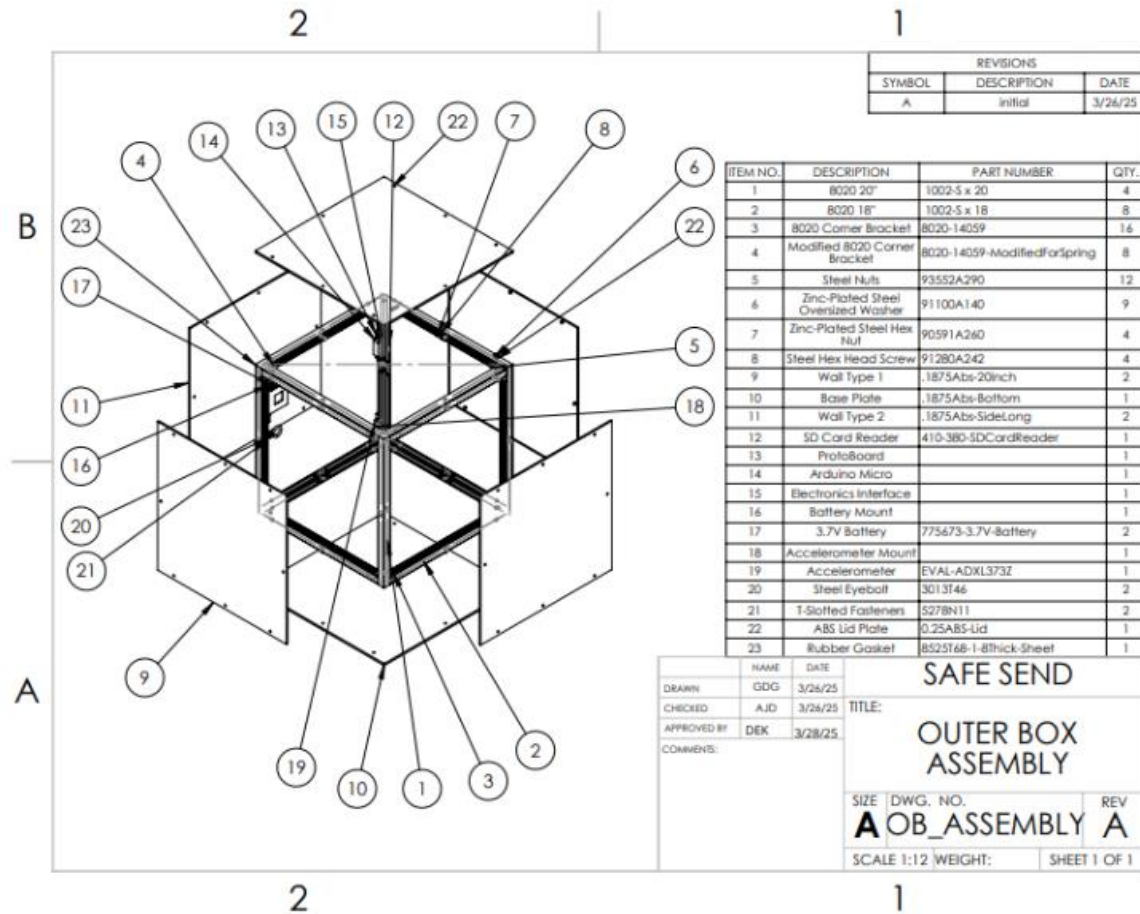
- 12 individual 80-20 extrusions make up the frame
  - Drilled
- Frame contains mounts for springs, wire rope, and electronics
- Panels attached to exterior
  - Water Jet
- 3D printed mounts and inner box



# Manufacturing Drawings

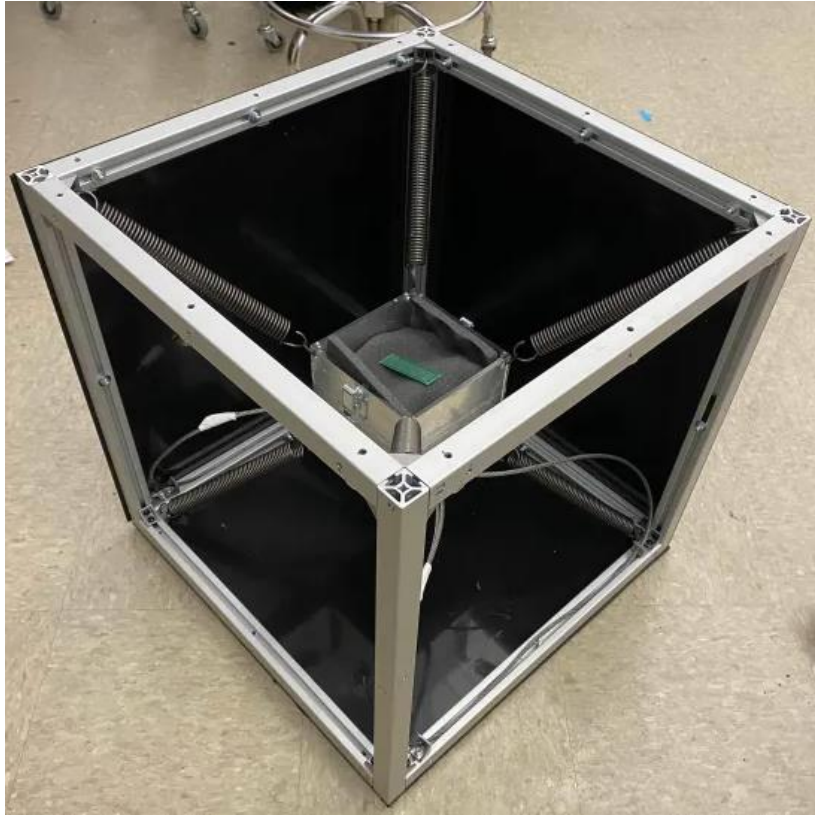


# Assembly - Drawings





# *Assembly - Results*



# Assembly - Changes

## Differences from CDR

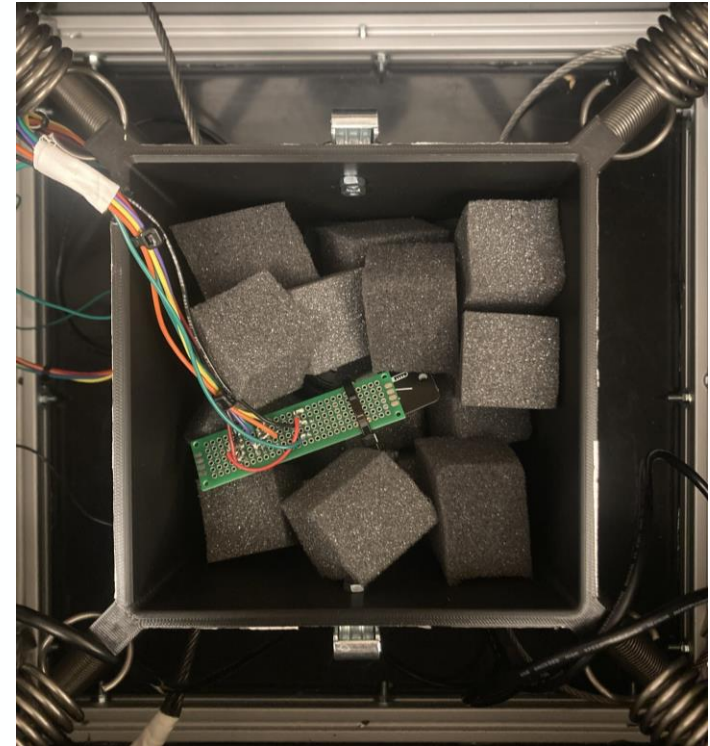
- Panel gaps observed during assembly
  - Epoxy didn't fully seal
- Edges taped with adhesive foil
  - Air barrier & water proofing
- Wire Rope Orientation
  - Loop shape to X formation
- Electronics Wiring
  - SPI Daisy Chain -> Iterate using code
  - Logic stepper



# Electronics & Sensing

## Wiring and Improvements

- Two sets of accelerometers and temp/humidity sensors write data to SD card
- 3 Protoboards soldered for tracking
  - Main housing had Arduino Micro, SD Card, and Logic Stepper
  - Each measurement apparatus held a DHT22 temperature and humidity sensor and a ADXL373 accelerometer using SPI communication
- Soldered connections improved data acquisition
- Improved wire quality which enhanced reliability





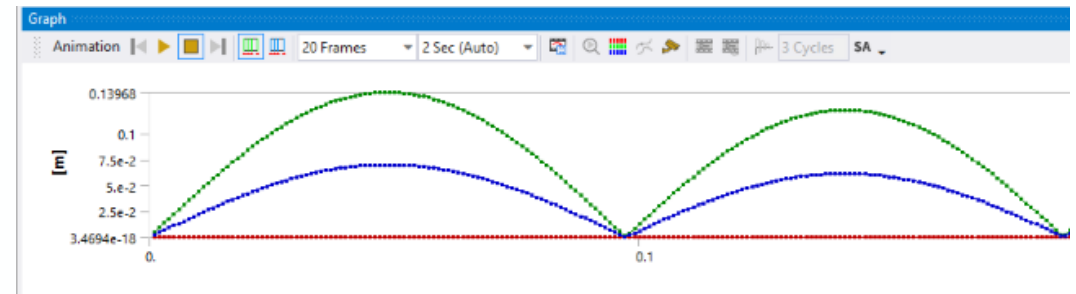
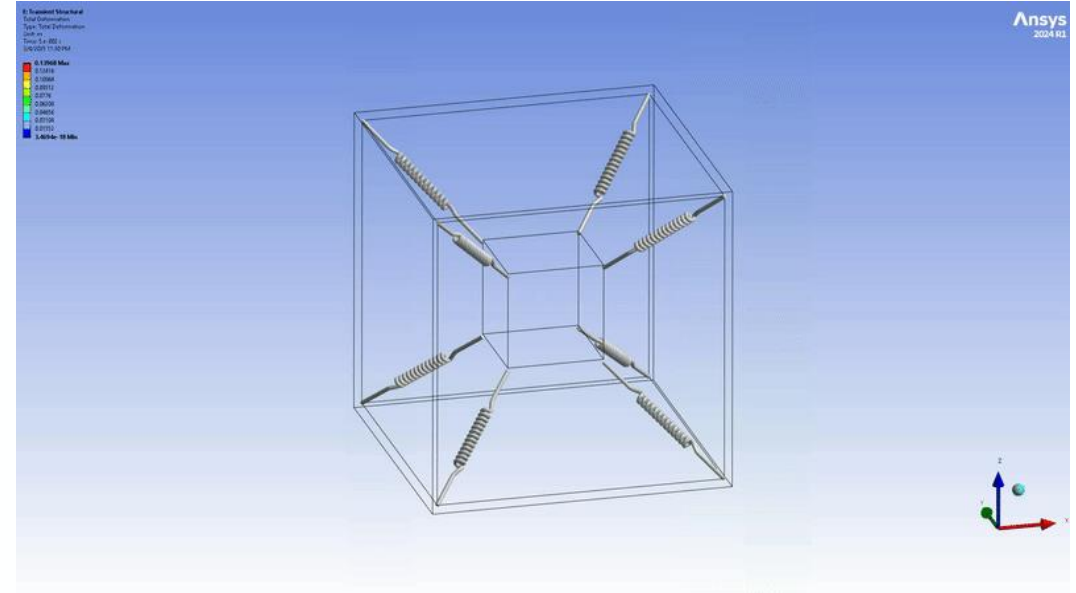
# ***Electronics Potential Improvements***

- Address acceleration data noise
  - PCB to ensure high-quality connections
- Improve data storage capacity
  - Test and implement accelerometer "wake up" mode to save data storage space
  - Increase storage size
- Improve ease of recharging for batteries
  - Charging from wall outlet



# Shock Analysis

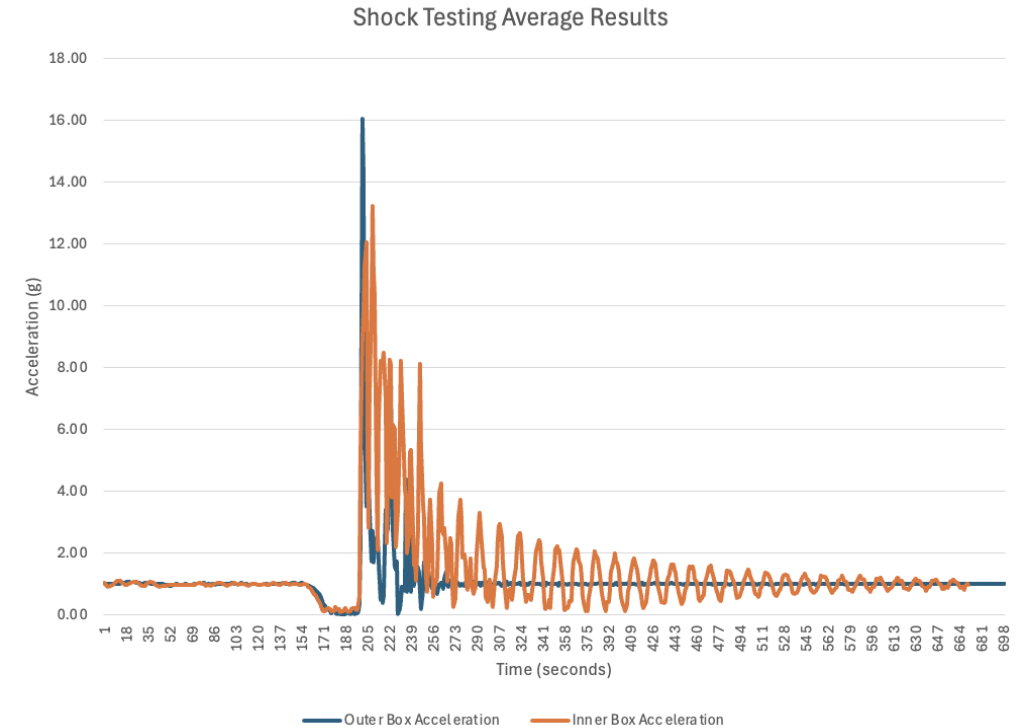
- ANSYS Transient Structural
- Simulates conditions of worst case 1 m drop
  - Input 4.43 m/s velocity
- Max displacement = 5.5 inches
- Meets max acceleration requirement (15 g)
- Used this result to drive spring selection
  - Minimum 500 N/m Spring
  - Dampers needed to stop vibration
    - Wire Rope



# Validation Testing

## Shock Testing

- Conducted 5 trials of 1 meter drop test
- Maximum acceleration of the outer box is 16.2 g
- Maximum acceleration of the inner box is 13.1 g
- Nearly a 97.38% decrease in loading based on calculated g-force
- **Meets requirement** of reducing shock to below 15 g



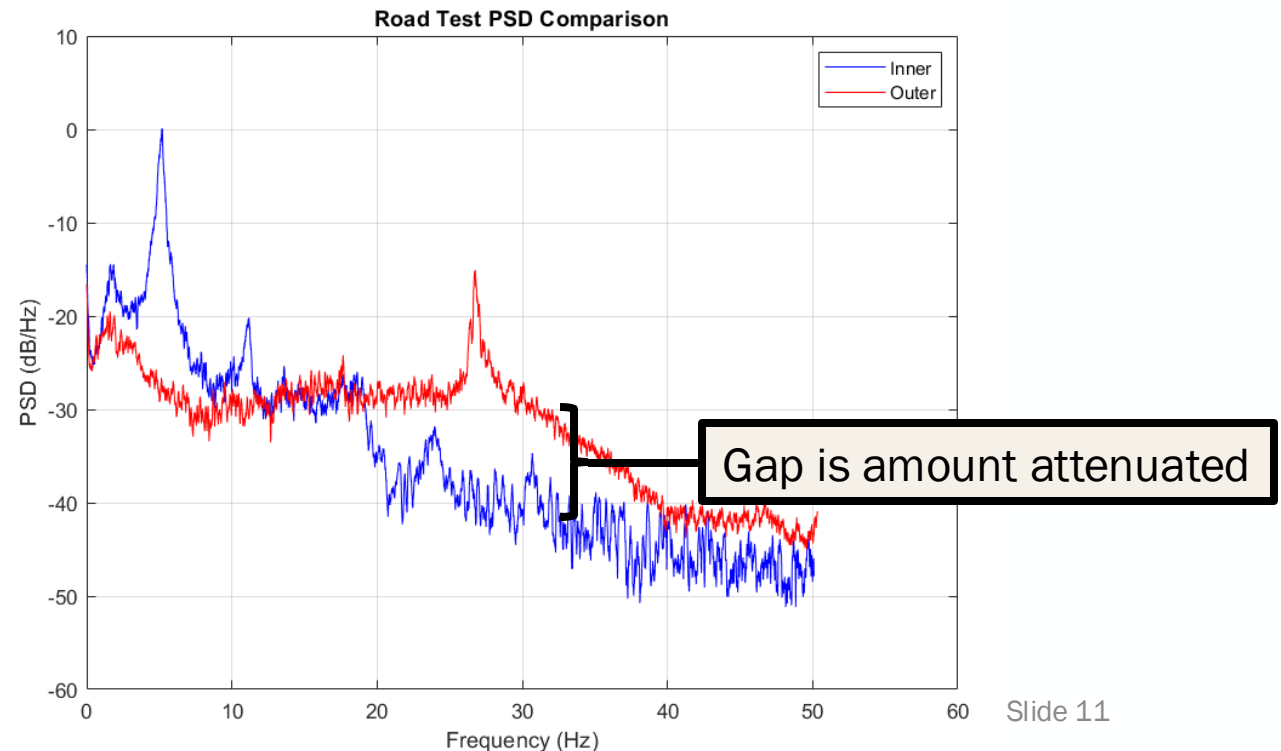
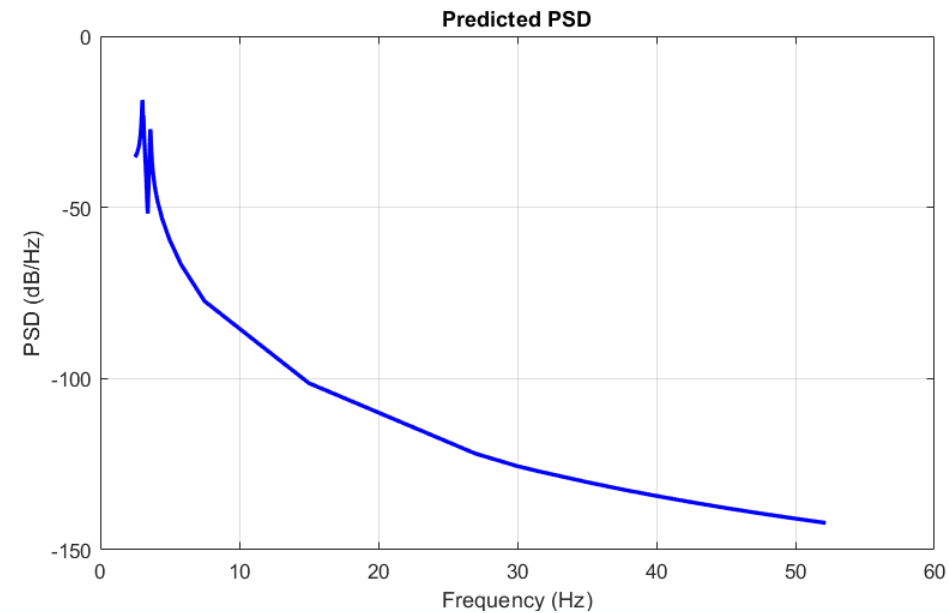
$$a = \frac{v^2}{2s} = \frac{(4.43)^2}{2 \times 0.002} = \frac{19.6}{0.004} = 4,900 \text{ m/s}^2$$

$$\text{G-force} = \frac{4,900}{9.81} \approx \boxed{500 \text{ g}}$$

# Validation Testing

## Vibration Testing

- 15-minute drive in car
- Shape of PSD is as predicted in the CDR
- Peak at 5 Hz instead of 3 Hz
- Attenuation starting at 10 Hz
  - 5 – 15 dB attenuation past 20 Hz
    - Meets 3 dB requirements
  - Inner box power is 3% to 31% of environment
    - Average of 10%

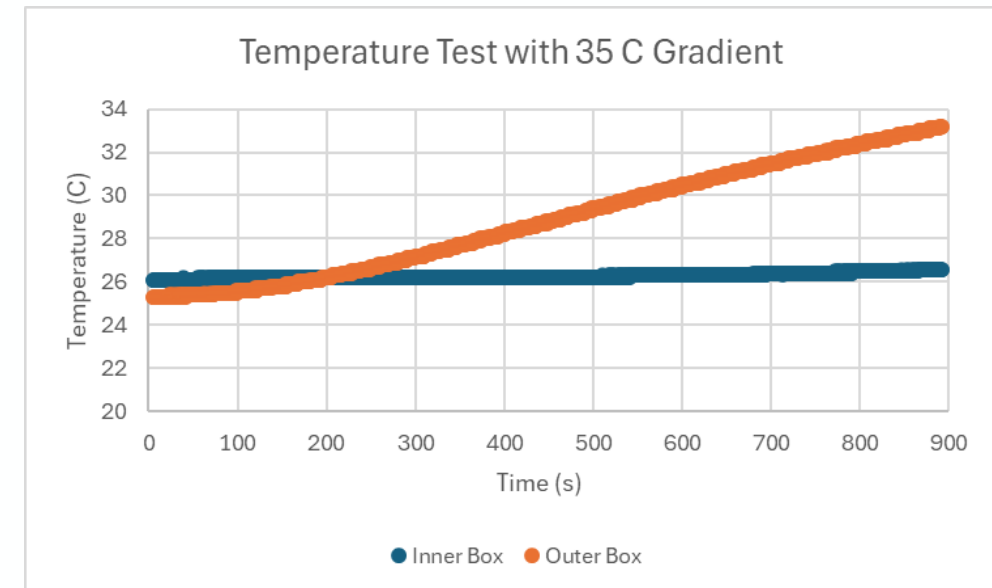
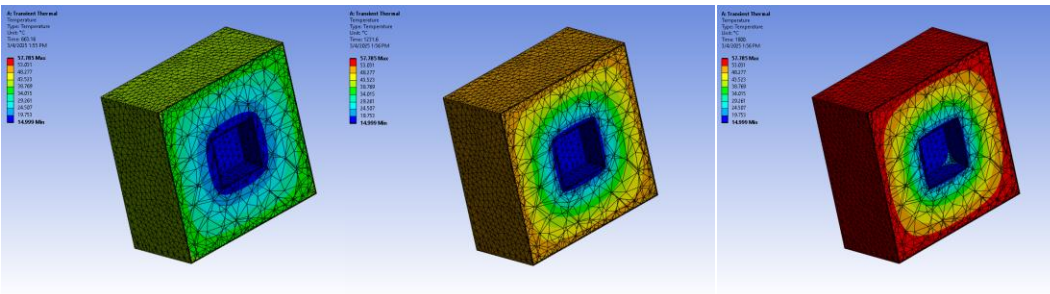




# Validation Testing

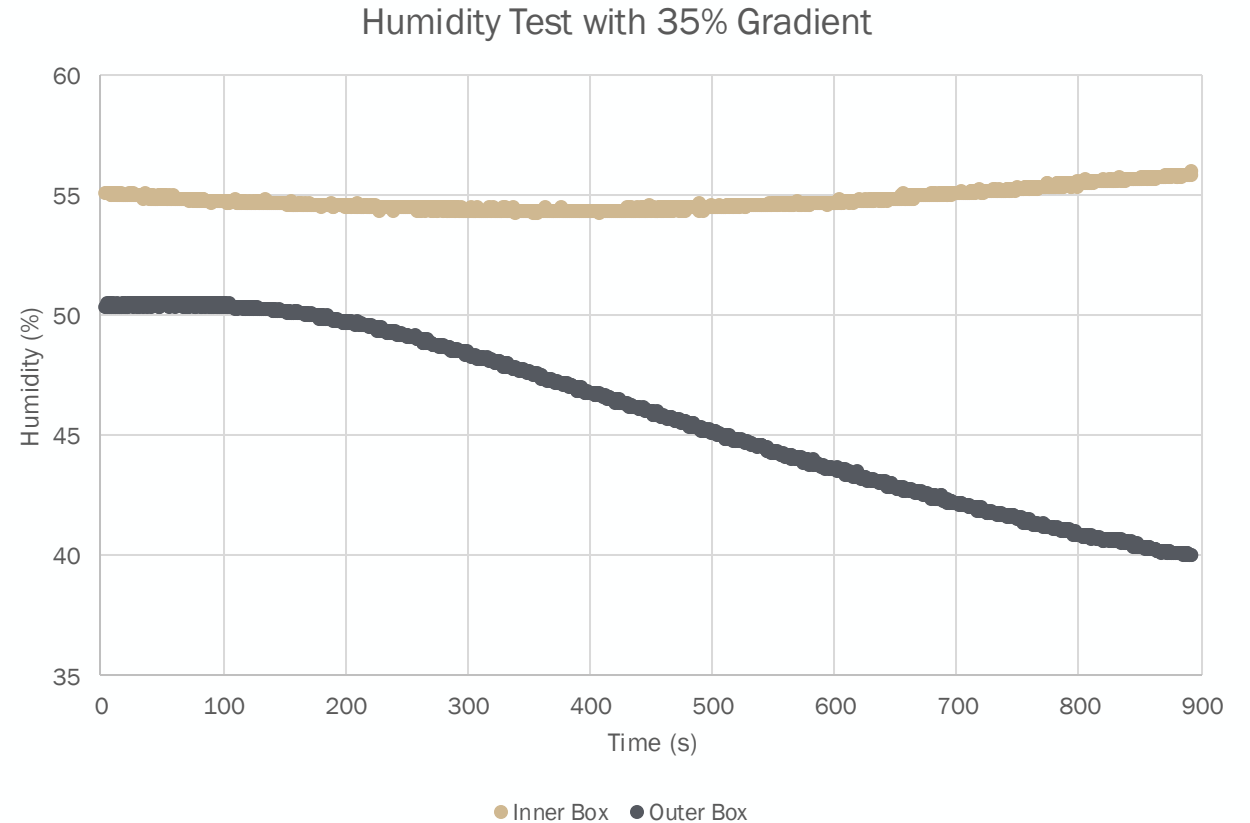
## Thermal Performance

- Box subjected to a 35° C temperature gradient in a sauna
- Inner box experienced 0.5° C increase from 26.1 to 26.6 in 15 minutes
  - 0.033° C/min
  - Estimated 0.042 °C/min at 45° C gradient
- Meets 0.5° C/min requirement
- Outer Box increased 7.9° C



# Humidity Testing

- Box subjected to a 35% humidity difference
  - Sauna less humid than ambient
- Inner box experienced extremely steady humidity
- Outer Box decreased by 10%
  - Absolute humidity stayed the same
- Unable to perform original waterproof testing due to poor alignment caused by insufficient rivet installation



# Requirements & Results Recap

## Shock:

Requirement: < 15 g with 1 meter drop

Result: 13.1 g



**Vibrations:** 3 dB attenuation above 10 Hz

Result: Negligible attenuation from 10 – 20 Hz



5 – 15 dB attenuation above 20 Hz



## Thermal:

Requirement: 0.5° C/min when subject to a 45° C temperature gradient

Result: 0.042° C/min



## Humidity:

Requirement: Humidity does not change when sprayed by water

Result: No change with 35% humidity gradient



# Business Proposition

## Renting Safe Send

- Safe Send will rent units out
- Assumptions:
  - Each device used 40 times a year
    - Every 9 days
  - 4405 devices in circulation
  - \$135.87 to make; \$598,507 upfront cost
- Revenue:
  - Rent for \$15 a day
  - \$15.86 million annual revenue
- Impact:
  - Protects delicate components
  - Relaxes design requirements

Sector	Annual Shipments	0.01% precision shipments	5% Market Share
MEMS Devices	34 Billion	3,400,000	170,000
Semiconductor	1.15 Billion	115,000	5,750
Medical Device	85 Million	8,500	425



# ***Design Improvements***

## **Frame**

- Injection molded foamed ABS frame
  - Fixes bolt alignment
  - New box is 18.5 lbs
- Handles

## **Vibrations**

- Foam/rubber mounts for springs and dampers

## **Electronics**

- Rechargeable battery
- Increased data storage
- Reduce data noise
- App for tracking



# *Thank You!*



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# Backup – Cost Estimate

## Sample Injection Molding Cost – Main Body

Injection Molded Body:

Material Cost:  $7741.92 \text{ cm}^3 \times 1.05 \text{ g/cm}^3 \times 0.00293 \text{ \$/g} = \$23.81$

Projected Area:  $2580.64 \text{ cm}^2$

Runner %: 5%

Shot area:  $2709.67 \text{ cm}^2$

Injection Pressure: 500 bar

8500 kN machine used

Cycle time

$T = 70 \text{ s}$

Mold Point System:

Base cost =  $50 + 0.023A \cdot h^{0.4} = 150 \text{ hours}$

Ejection hours  $2.5 \cdot A^{0.5} = 30 \text{ hours}$

Geometric complexity: 30 surface patches, 15 hours

10% increase for not critical finish, 2% for tolerance

Mold Cost = 218.4 hours = \$8736

Total Cost =  $(Nt/n)(k_1+m_1F)t + C_1n^{0.766} + NtC_m$

Cost = \$27.70 per part

# Final Cost Estimate

Component	Average Unit Cost (USD)
Microcontroller (Arduino-equivalent)	\$2.00
Accelerometer (high sample rate)	\$1.75
Humidity + Temp sensor	\$1.25
Battery	\$2.00
PCB Fabrication (2-layer)	\$1.50
Assembly + Passives	\$3.00
Firmware flashing + Testing	\$1.50
Overhead/Buffer	\$1.50
<b>Total per unit</b>	<b>\$11.50</b>

Bought in bulk for 4500 units

Springs: \$0.75 per spring = \$6

Wire Rope: \$4.50 for 10 feet

Rubber Gasket: \$14

Fasteners: \$3

Injection Molded Costs:

Body: \$27.70

Lid: \$7.97

Inner Box: \$6.55

Assembly time: 60 minutes = \$30

Total Cost (with 20% fudge factor) = \$135.87 per unit



# Eng requirements

Engineering Requirements	Metric	Units
<b>Thermal Insulation</b>		
Designed for range of outdoor temperatures	-29 to 57	Celsius
Inside shall be below a temperature change of less than 0.5 C/min given a temperature gradient of 45 C	0.5	C/min
<b>Shock</b>		
The package shall resist shock from 1 meter flat and corner drop test, limiting package acceleration to 15 g's.	15	g
<b>Vibrations</b>		
Natural frequencies of fragile components are attenuated >100 Hz	-3	dB
Natural frequencies of shock/vibration isolation system are attenuated ~10 Hz	-3	dB
<b>Environment</b>		
Package shall withstand water up to 0.5m for 30 minutes	0.5	m
Avoid using materials that could produce particulate	n/a	n/a
<b>Tracking</b>		
Product shall track any vibrational and thermal disturbances throughout the whole shipping duration	3	days
<b>Customer Requirements</b>		